

Title (en)

SYSTEM FOR CATION-ELECTRON INTRUSION AND COLLISION IN A NON-CONDUCTIVE MATERIAL

Title (de)

SYSTEM ZUR KATIONEN-ELEKTRONEN-INTRUSION UND KOLLISION IN EINEM NICHTLEITENDEN MATERIAL

Title (fr)

SYSTEME D'INTRUSION ET DE COLLISION CATION-ELECTRONS DANS UN MATERIAU NON-CONDUCTEUR

Publication

EP 1786724 A1 20070523 (FR)

Application

EP 05778671 A 20050615

Priority

- FR 2005001499 W 20050615
- FR 0406477 A 20040615

Abstract (en)

[origin: WO2006003328A1] The invention concerns a device for intrusion of H⁺ ions and electrons inside a non-conductive material (2) so as to promote their low-energy collisions. More particularly, the invention concerns a device for colliding at least one H⁺ ion and at least one electron from a hydrogen-containing compound (3) and at least one cathode (4). The invention is characterized in that it comprises at least one electromagnetic field generator for extracting said H⁺ ion from said hydrogen-containing compound (3) and transferring said H⁺ ion to said cathode (4); at least one non-conductive material positioned between at least part of said hydrogen-containing compound and said cathode, said collision being produced inside said non-conductive material (2).

IPC 8 full level

C01B 3/00 (2006.01); **C04B 35/5833** (2006.01); **C04B 41/53** (2006.01); **C25B 1/02** (2006.01)

CPC (source: EP US)

C01B 3/0005 (2013.01 - EP US); **C01B 3/02** (2013.01 - EP US); **C01B 3/04** (2013.01 - EP US); **H01M 8/065** (2013.01 - EP US); **H01M 8/186** (2013.01 - EP US); **Y02E 60/32** (2013.01 - EP US); **Y02E 60/36** (2013.01 - EP US); **Y02E 60/50** (2013.01 - EP US)

Citation (search report)

See references of WO 2006003328A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

FR 2871478 A1 20051216; **FR 2871478 B1 20061222**; AU 2005259043 A1 20060112; AU 2005259043 A2 20060112; AU 2005259043 B2 20110310; CA 2570060 A1 20060112; CN 101010255 A 20070801; CN 101010255 B 20110629; EP 1786724 A1 20070523; JP 2008502568 A 20080131; JP 4964766 B2 20120704; US 2008160359 A1 20080703; US 8083904 B2 20111227; WO 2006003328 A1 20060112

DOCDB simple family (application)

FR 0406477 A 20040615; AU 2005259043 A 20050615; CA 2570060 A 20050615; CN 200580019823 A 20050615; EP 05778671 A 20050615; FR 2005001499 W 20050615; JP 2007516000 A 20050615; US 57055505 A 20050615